## **HE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No	09/756,971
Filing Date J	lanuary 9, 2001
Inventorship	Salman Akram
Assignee Micron T	echnology, Inc.
Group Art Unit	2827
Examiner Da	avid A. Zarneke
Attorney's Docket No	MI22-1572
Title: Methods of Forming Board-On-Chip Packages	

## TERMINAL DISCLAIMER

To: Mail Stop Fee Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

I, D. Brent Kenady, residing at Spokane, Washington, represent that I am the attorney of record for Micron Technology, Inc., a corporation of the State of Delaware. Micron Technology, Inc. is the owner of all right, title and interest of this U.S. Patent Application Serial No. 09/756,971, filed January 9, 2001, as evidenced by an assignment recorded September 2, 1999, at Reel 010227, Frames 0492-0496 in the U.S. Patent and Trademark Office.

Micron Technology, Inc. is also the owner of all right, title and interest in U.S. Patent No. 5,817,535 as evidenced by an assignment recorded June 25, 1996, at Reel 8072, Frame 0354 in the U.S. Patent and Trademark Office.

Micron Technology, Inc. is also the owner of all right, title and interest in U.S. Patent No. 6,214,641 as evidenced by an assignment recorded June 25, 1996 at Reel 8072, Frame 0354 in the U.S. Patent and Trademark Office.

\$7/09/2003 TBESHAH1 00000033 09756971

PAT-US\TD-01

The evidentiary documents (the assignments) have been reviewed, and I certify that, to the best of assignee's knowledge and belief, title is in the assignee seeking to take this action.

Micron Technology, Inc. hereby disclaims the terminal part of any future patent granted on this U.S. Patent Application Serial No. 09/756,971 which extends beyond the expiration date of U.S. Patent Nos. 5,817,535 and 6,214,641, and further hereby agrees that any future patent so granted on this U.S. Patent Application Serial No. 09/756,971 shall be enforceable only for and during such period that the legal title to U.S. Patent Nos. 5,817,535 and 6,214,641 shall be the same as the legal title to any patent issued from U.S. Patent Application Serial No. 09/756,971. This agreement is to run with any patent granted on the application and is to be binding upon the grantee of such patent and its successors or assigns.

Micron Technology, Inc. does not disclaim any terminal part of any patent granted on this application prior to the expiration date of the full statutory term of the United States Patent Nos. 5,817,535 and 6,214,641 in the event that they later expire for failure to pay a maintenance fee, are held unenforceable, are found invalid by a court of competent jurisdiction, are statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. §1.321(a), have all claims canceled by a reexamination certificate, are reissued in any matter or are otherwise terminated prior to expiration of its full statutory term as presently shortened by any terminal disclaimer, except for the separation of legal title stated above.

 The fee required by 37 C.F.R. 1.20(d) is submitted herewith. The Commissioner is hereby authorized to charge payment of any additional fees or credit overpayments to Deposit Account No. 23-0925.

Dated: 7-3-93

By:

D. Brent Kenady Reg. No. 40,045